

TECHNICAL BULLETIN

PRODUCT: POLYSET™ 9000

POLYSET™ 9000 is a solid high molecular weight bismaleimide resin. At ambient temperature, POLYSET™ 9000 behaves like a thermoplastic. However, at temperatures in excess of 100° C (in the presence of a suitable free radical catalyst) thermoset cure occurs. POLYSET™ 9000 exhibits excellent low shrinkage properties, high hydrolytic stability, and high thermal stability (TGA decomposition onset is greater than 400° C).

POLYSET™ 9000 is recommended for adhesive applications and can be used as an additive to promote adhesion to difficult substrates such as polyolefins, ceramics, aluminum, and other metals. POLYSET™ 9000 is incompatible with ketones. It can be dissolved in aromatic solvents and, under heat (80° C), it will dissolve into reactive diluents such as isobornyl methacrylate.

PHYSICAL PROPERTIES:

Appearance Light golden brown powder

Density (g/cm³) 1.1950 ± 0.0025

Weight loss (TGA @ 300°C) < 1.0%

Molecular weight (avg.) >5000 g/mol. Weight Solids >99.9%

For further information, please direct your inquiries to:

Designer Molecules Inc. 10090 Willow Creek Road San Diego, CA 92131

Contact: Sharon Hanson Phone: (858) 536-4703 Fax: (858) 348-1123

E-mail: <u>shanson@designermoleculesinc.com</u>

Web page: www.designermoleculesinc.com